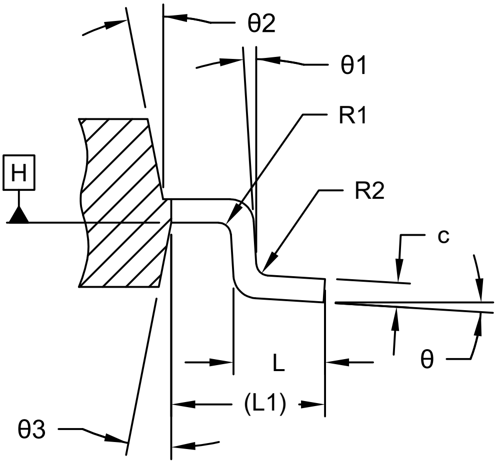
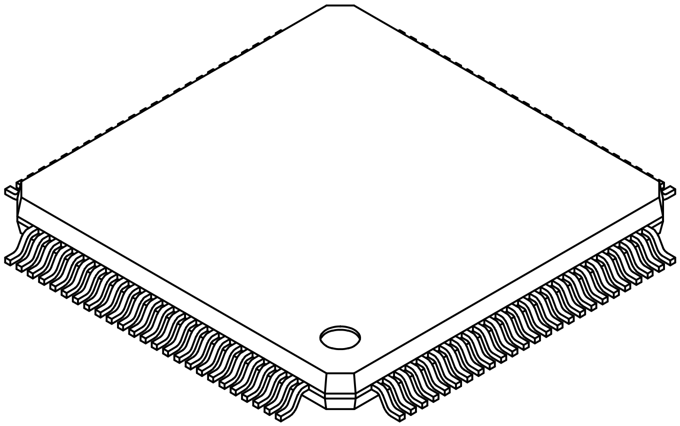
100-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1 mm Body [TQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Standoff	A1	0.05	–	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Overall Length	D	14.00 BSC		
Molded Package Length	D1	12.00 BSC		
Overall Width	E	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Lead Width	b	0.13	0.18	0.23
Lead Thickness	c	0.09	–	0.20
Lead Bend Radius	R1	0.08	–	–
Lead Bend Radius	R2	0.08	–	0.20
Foot Angle	θ	0°	–	7°
Lead Angle	θ1	0°	–	–
Mold Draft Angle	θ2	11°	12°	13°
Mold Draft Angle	θ3	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.